

IPP Cool Chip Products Application Note

❖ General Notes:

- Data and specifications apply when part is mounted in IPP test fixture.
- Flangeless devices are compatible with most solders designed for attachment to silver. The solder used to mount flangeless devices should be chosen for individual application and environmental conditions.
- Solder edges to RF lines and ground using lead free or Sn63 alloy with appropriate flux.
- Cool Chips have two versions available, with edge wrap and without edge wrap.
- **Temperature Conductivity (TC):** 2-6 °C/W

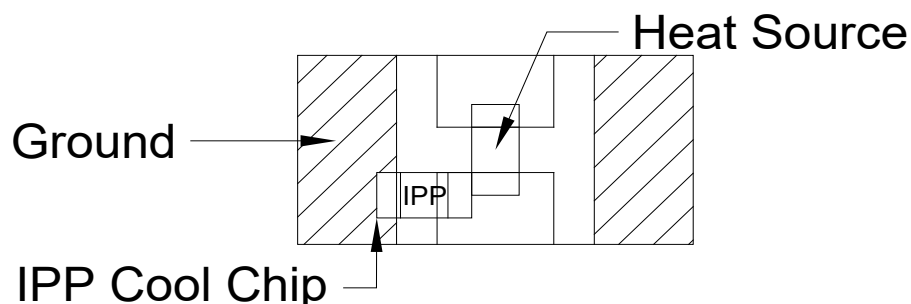
❖ Package Styles

- In general there are three package styles, .08x.05, .100x.100, and .120x.060. Parts are designed to be soldered directly to the heat sink.



❖ Cool Chip Materials

- **Substrate:** ALN Substrate
- **Finish:** Gold over Nickel



MOUNTING VIEW

Electrical Specifications

Capacitance: Each Cool Chip has a series capacitance of <0.1 pF with the edge wrap and a shunt capacitance of 0.1 pF with edge wrap.

Temperature Conductivity (TC): The temperature conductivity is the amount of temperature change per watt. Depending on which size is chosen, and if edge wrap or no edge wrap is chosen, it could have a $2-6$ °C/W. Edge wrapped parts generally have a higher heat transfer than non-edge wrapped parts.